

REMARKS

Claim 8 has been amended. A new claim 14, with limitations similar to those of previously canceled claimed 5 but depending from claim 3, has been added. Claim 13 has been canceled, making the indefiniteness rejection thereof moot. Reconsideration and reexamination of the amended application respectfully are requested.

Independent claim 3 and depending claims 4 and 6 are rejected under 35 USC § 103(a) as being unpatentable over *Sasaki et al.* in view of *Tanaka et al.* and *Eguchi et al.* The rejection respectfully is traversed.

Sasaki et al. disclose a semiconductor device having a semiconductor chip 1, a resin film 2 and a bump 3. The circuit formation surface 1X of a semiconductor substrate 1A is covered with a surface protective film 1D typically made of resin of the polyimide group, and the back surface 1Y of the semiconductor substrate 1A is covered with the resin film 2 typically made of a thermosetting resin of epoxy group. However, *Sasaki et al.* are silent about the elasticity and strength of the surface protective film 1D and the resin film 2. Therefore, *Sasaki et al.* naturally fail to disclose or suggest the relationship, with regard to elasticity or strength between the surface protective film 1D and the resin film 2.

As stated in the Action, *Tanaka et al.* teach a Young's modulus from 2600 MPa to 6 GPa for the polyimide used in their invention, and *Eguchi et al.* teach an elastic modulus at room temperature in the range of 500 MPa to 25 GPa for a thermosetting resin used in their invention. However, both references, whether taken alone or in combination, fail to disclose or suggest the relationship in either elasticity or strength between two resin films respectively formed on the opposite surfaces of a semiconductor substrate.

In view of the above, the applicants cannot see how one of ordinary skill in the art would have been motivated to combine the three references to make up a structure as recited in the claim 3. Therefore, claim 3, and claims 4 and 6 depending therefrom are deemed clearly to be patentable of these references, and the rejection accordingly should be withdrawn.

Independent claim 8 and depending claims 9 and 10 are rejected under 35 USC §102(e) as anticipated by *Wakamiya et al.* (US Patent Publication No. 2002/0041013). Claim 8 has been amended in order to clarify that the gold portion of the post is in direct contact with the passivation film/resin film interface. By this amendment, claim 8 is clearly distinguishable from the teachings of *Wakamiya et al.* as explained below. The rejection therefore is inapplicable to the amended claim.

That is, whereas amended claim 8 recites that the gold portion of the post is in direct contact with the passivation film/resin film interface, no part of the gold stress-absorbing layer 10 of *Wakamiya et al.* is in contact with a passivation film/resin film interface, and accordingly, *Wakamiya et al.* does not meet this requirement of the claim. The gold stress-absorbing layer 10 of *Wakamiya et al.*, which is provided at the middle of a post 4, is separated from the interface between a coating layer 7 and the protective dielectric layer 3 as well as from the interface between the protective dielectric layer sealing resin 5 and the protective dielectric layer 3. Thus, the stress-absorbing layer 10 fails to meet the gold portion of the post in the present invention of amended claim 8 that requires the gold portion be in direct contact with the passivation film/resin film interface.

It is also noted that this feature of the invention, as claimed in claim 8, has the advantage that shearing stress applied to the junction portion between the post and the

electrode pad is more effectively reduced than in the case of the *Wakamiya et al.* structure. Claim 8, and claims 9 and 10 depending therefrom, are deemed clearly to be patentable over *Wakamiya et al.* and the rejection accordingly should be withdrawn.

The Examiner also rejected claims 11 and 12 under 35 USC 103(a) as being unpatentable over *Wakamiya et al.* in view of *Shieh*. The rejection respectfully is traversed. Claims 11 and 12 depend from claim 8. *Shieh* fails to disclose the features of invention missing from *Wakamiya et al.* discussed above with regard to the rejection of claim 8. Therefore, claims 11 and 12 are deemed clearly to be patentable for at least the reasons advanced above as to the patentability of claim 8, and the rejection accordingly should be withdrawn.

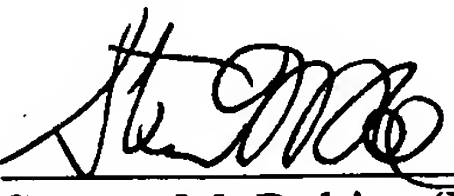
Based on the above, it is submitted that the application is in condition for allowance and such a Notice, with allowed claims 3, 4, 6, 8 - 12 and 14, earnestly is solicited.

Should any fee be required, please charge the same to our Deposit Account No. 18-0002 and advise us accordingly.

Respectfully submitted,

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Date

SMR/


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